

WHAT IS CLAIMED IS:

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1. A resin coating method for applying resin to a predetermined region of a printed wiring board comprising the steps of:

10 imaging an external appearance of the resin extruded from a resin application device; and
 automatically adjusting an amount of the resin extruded from the resin application device based on the external appearance of the resin obtained in the imaging step.

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2. The resin coating method as claimed in claim 1, further comprising the steps of:

20 stretching the resin atop a stage prior to the imaging step; and
 measuring a surface area of the resin developed atop the stage after the imaging step
25 using an image analyzer.

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3. The resin coating method as claimed in claim 1, wherein the imaging step comprises exposing the resin to light of a predetermined wavelength so as to fluoresce the resin and separating fluorescent light so generated from light of other wavelengths
35 to obtain a fluorescent image of the resin.

7. A resin coating method for applying resin to a predetermined region of a printed wiring board, comprising the steps of:

- 5 imaging a residual amount of the resin on an extrusion nozzle of a resin application device from which the resin is expelled; and
 washing the nozzle when the residual amount exceeds a predetermined amount.

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8. A resin coating apparatus for applying resin to a predetermined region of a printed wiring board, comprising:

- an imaging unit for imaging an external appearance of the resin extruded from the resin coating apparatus; and
20 an automatic adjustment unit for automatically adjusting an amount of the resin extruded from the resin coating apparatus based on the external appearance of the resin obtained in the imaging step.

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9. A resin coating apparatus for applying resin to a predetermined region of a printed wiring board, comprising:

- a temperature sensor for measuring a temperature of an extrusion nozzle of the resin coating apparatus; and
35 an automatic adjustment unit for adjusting an amount of the resin extruded from the resin coating apparatus based on the temperature of the

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nozzle.

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10. A resin coating apparatus for applying a resin to a predetermined region of a printed wiring board, comprising:

10 a positioning unit for positioning a tip of an extrusion nozzle of the resin coating apparatus at a predetermined reference height.

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11. A resin coating apparatus for applying resin to a predetermined region of a printed wiring board, comprising:

20 an imaging unit for imaging an external appearance of a resin drop after the resin drop has been expelled from an extrusion nozzle of the resin coating apparatus but before the resin drop contacts the printed wiring board; and

25 an adjustment unit for adjusting a distance between a tip of the extrusion nozzle and the printed wiring board based on the external appearance of the resin drop.

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12. A resin coating apparatus for applying resin to a predetermined region of a printed wiring board, comprising:

35 an imaging unit for imaging a residual amount of the resin on an extrusion nozzle of the resin coating apparatus; and

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a washing unit for washing the nozzle when
the residual amount exceeds a predetermined amount.

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